

2. (original) A conductive contact member according to claim 1, wherein said layer is formed by plating.
3. (canceled)
4. (previously presented) A conductive contact member according to claim 1, wherein silver is added to gold by 0.01% to 8%.
5. (previously presented) A conductive contact member according to claim 1, wherein said conductive contact member is selected from the group consisting of a coil, needle member having a pointed end, and rod member having a flat end.
6. (original) A conductive contact member according to claim 1, wherein said conductive contact member is made of steel.
7. (original) A conductive contact member according to claim 1, wherein said conductive contact member is in the form of a compression coil spring, and said solder resistant layer is formed around a coil wire forming said coil spring.
8. (original) A conductive contact member according to claim 1, wherein said conductive contact member is in the form of a compression coil spring having a contact part consisting of closely wound turns of a coil wire, and said solder resistant layer is formed over an outer surface of said closely wound turns of the coil wire.
9. (new) A conductive contact member for establishing an electric contact by being applied to an object to be contacted that includes solid solder, comprising a layer of highly electrically conductive material resistant to solder deposition and essentially consisting of an alloy of gold added with silver, the layer being formed at least over a conductive contact part of said conductive contact member so that said conductive contact part of said conductive contact member may not be contaminated by deposition of solder from said object to be contacted.

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10. (new) A conductive contact member for establishing an electric contact by being applied to an object to be contacted that includes solid solder, comprising a layer of highly electrically conductive material resistant to solder deposition and essentially consisting of a homogeneous mixture of gold added with silver, the layer being formed at least over a conductive contact part of said conductive contact member so that said conductive contact part of said conductive contact member may not be contaminated by deposition of solder from said object to be contacted.

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